

L-323

Foaming Core Splice, Dual Temperature Cure



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Product Data Sheet

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Description

L-323 is dual-temperature cure, intumescent film adhesive formulated to splice honeycomb core to adjacent close-out members or splice individual sections of honeycomb together in the manufacture of sandwich structures. L-323 is compatible with most 250°F (121°C) and 350°F (176°C) curing adhesive systems. L-323 will not sag or slump during the curing process. The expansion of L-323 is approximately 2.5-3.0 times the original thickness.

Advantages of L-323

- ❖ L-323 allows the designer to use various core densities within a single sandwich to meet specific local load conditions.
- ❖ L-323 acts to stabilize honeycomb core materials when interfacing with adjacent structural members in the transfer of shear loads.

Physical Properties

- *Form:* *Pliable Film*
- *Standard Weight:* *0.300 lbs/ft² (1464 g/m²) (other weights are available)*
- *Standard Thickness:* *0.050" (1.27 mm)*
- *Volatile Content:* *Less than 0.5%*
- *Color:* *Tan*

Availability

- *Sheets 1' x 2' (30 cm x 61 cm)*

Shelf Life

- *14 days at Room Temperature (75°F or 24°C)*
- *3 months at 40°F (4°C)*
- *12 months at 10°F (-12°C)*

Cure Cycles

- 15 minutes at 350°F (176°C), or
- 40 minutes at 275°F (135°C), or
- 60 minutes at 250°F (121°C), or
- 90 minutes at 235°F (113°C).

Average Mechanical Properties

Core Shear Strength using 0.500" Thickness, 1/8" cell (1.27 cm, 3.18 mm) 5052 Al per Mil-C-7438

- -67°F (-55°C) 850 PSI (5.9 MPa)
- RT 1,470 PSI (10.1 MPa)
- 180°F (82°C) 1,400 PSI (9.7 MPa)
- 350°F (176°C) 1,280 PSI (8.8 MPa)

Tube Shear Strength using 5052 Aluminum, 1.0" (2.54 cm) outer diameter, 0.5" (1.27 cm) inner diameter, 0.049" (1.25 mm) thickness Aluminum tubing.

- RT 1,300 PSI (9.0 MPa)
- 250°F (121°C) 610 PSI (4.2 MPa)
- 350°F (176°C) 600 PSI (4.1 MPa)

Note: L-323 should be allowed to reach room temperature before removing from protective packaging to avoid moisture condensation on the film surface.

NOTICE:

Product data and parameters cited in this publication have been obtained in J.D. Lincoln, Inc. laboratories using the materials under carefully controlled conditions. The information, therefore, is believed to be accurate and correctly stated. Data of this type may be considered to be indicative of representative properties obtainable. J.D. Lincoln, Inc. cannot accept responsibility for the misapplication of these products, nor for their use under uncontrolled conditions. Numerical values resulting from the application of this material are dependant on processing details. It is recommended that the user develop his or her own application techniques and generate data consistent with his or her specific application and process.